



PMEG4002EB

200 mA very low VF MEGA Schottky barrier rectifier

28 June 2016

Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface Mounted Device (SMD) plastic package.

2. Features and benefits

- Forward current: 200 mA
- Reverse voltage: 40 V
- Very low forward voltage
- Ultra small and flat lead SMD plastic package
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current		-	-	200	mA
V_R	reverse voltage		-	-	40	V
V_F	forward voltage	$I_F = 200 \text{ mA}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$	-	520	600	mV

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SOD523	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.



6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4002EB	SOD523	plastic surface-mounted package; 2 leads	SOD523

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4002EB	L9

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	40	V
I_F	forward current		-	200	mA
I_{FRM}	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
I_{FSM}	non-repetitive peak forward current	half sine wave; $t_p = 8.3$ ms	-	1	A
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	150	°C
T_{stg}	storage temperature		-65	150	°C

9. Thermal characteristics

Table 6. Thermal characteristics

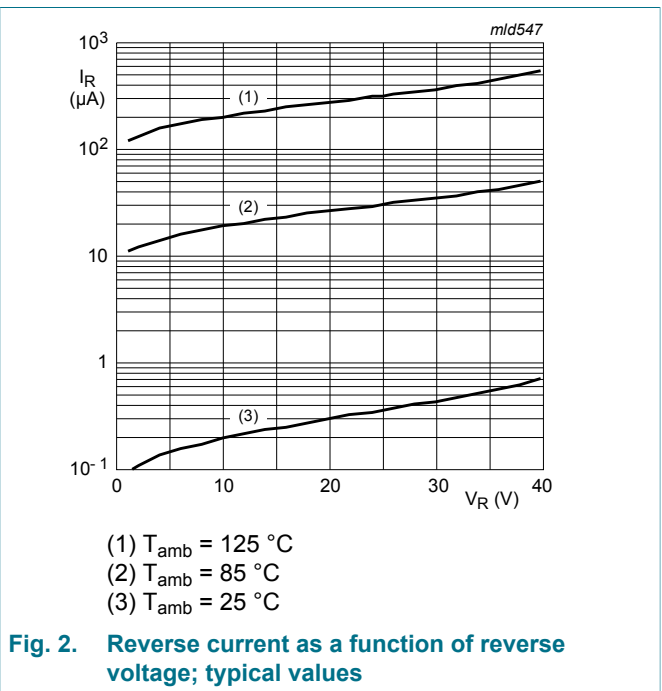
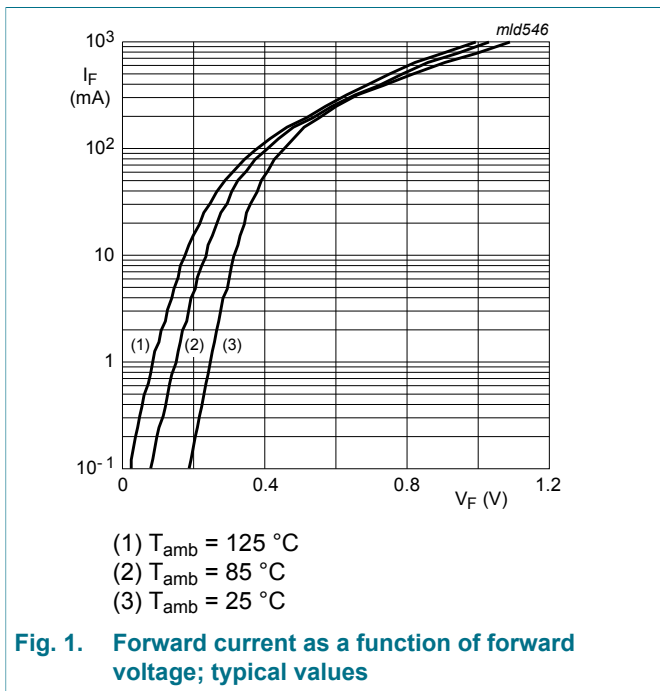
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	450	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		-	-	-	

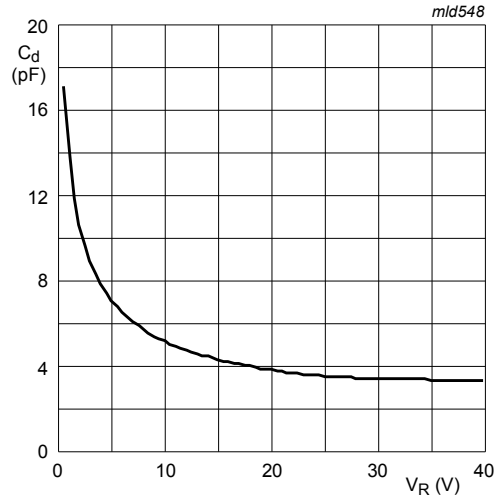
- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
 [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 0.1 mA; T _{amb} = 25 °C	-	190	220	mV
		I _F = 1 mA; T _{amb} = 25 °C	-	250	290	mV
		I _F = 10 mA; T _{amb} = 25 °C	-	320	360	mV
		I _F = 100 mA; T _{amb} = 25 °C	-	440	500	mV
		I _F = 200 mA; T _{amb} = 25 °C	-	520	600	mV
I _R	reverse current	V _R = 25 V; t _p ≤ 300 μs; δ ≤ 0.02 ; pulsed; T _{amb} = 25 °C	-	-	0.5	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _{amb} = 25 °C	-	20	-	pF





f = 1 MHz; T_{amb} = 25 °C

Fig. 3. Diode capacitance as a function of reverse voltage; typical values

11. Test information

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

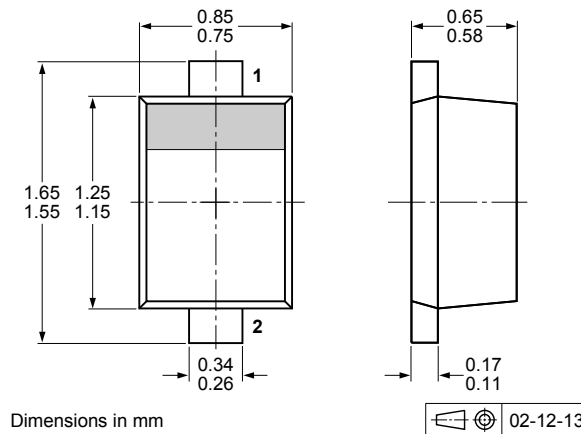


Fig. 4. Package outline SOD523

13. Soldering

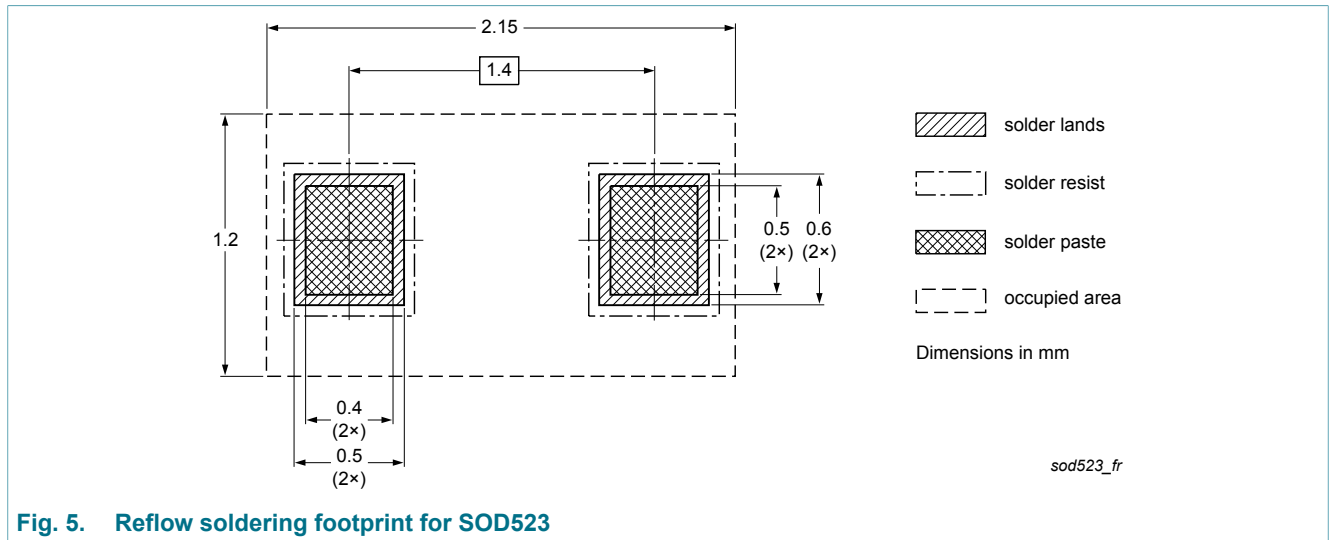


Fig. 5. Reflow soldering footprint for SOD523

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4002EB v.3	20160628	Product data sheet	-	PMEG4002EB v.2
Modifications:	<ul style="list-style-type: none">• Section "Features and benefits": added AEC-Q101 qualified• Section "Test information": added			
PMEG4002EB v.2	20100113	Product data sheet	-	PMEG4002EB v.1
PMEG4002EB v.1	20050712	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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16. Contents

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	1
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	2
9. Thermal characteristics.....	2
10. Characteristics.....	3
11. Test information.....	4
12. Package outline.....	4
13. Soldering.....	5
14. Revision history.....	6
15. Legal information.....	7

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